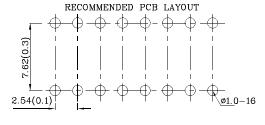
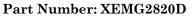


Features

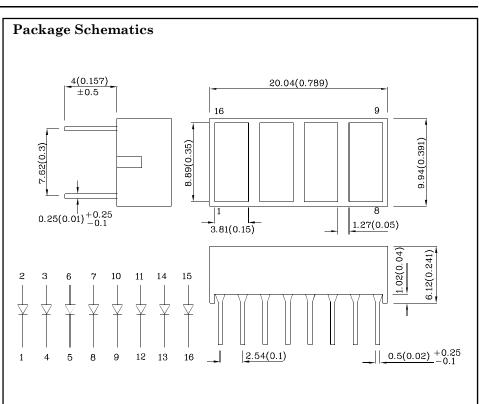
- \bullet Robust package
- \bullet Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- RoHS compliant







8.89mmx3.81mm LED LIGHT BAR



Notes: 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted. 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		MG (GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$I_{\rm F}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	Cycle ifs		mA	
Power Dissipation	P_{D}	62.5	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

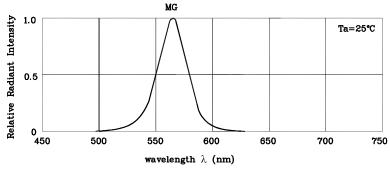
Operating Characteristics (T _A =25°C)	MG (GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2.2	V
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	$_{\rm pF}$

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λΡ	Lens-color
			min.	typ.		
XEMG2820D	Green	GaP	12 3*	24 7*	565*	Green Diffused

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Mar 11,2014

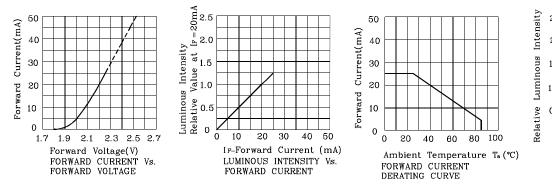
XDSA1987 V6-X Layout: Maggie L.

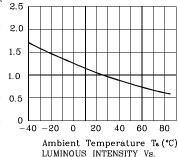




RELATIVE INTENSITY Vs. CIE WAVELENGTH

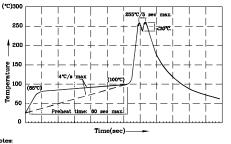
♦ MG







Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



nmend pre-heat temperature of 105°C or less (as measured with a noccupie attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 260°C wave soldering temperature between $245°C \sim 255°C$ for 3 sec (5 sec 1. Rec the wave 2.Peak

2.Peak wave soldering temperature between 245°C ~ 255°C for 3 secmax).
3.Do not apply stress to the epoxy resin while the temperature is a 4.Fixtures should not incur stress on the component when mounting during soldering process.
5.SAC 305 solder alloy is recommended.
6.No more than one wave soldering pass.
7.During wave soldering, the PCB top-surface temperature should be kept below 105°C. while the temperature is ab component when mounting 85°C

Remarks:

If special sorting is required (e.g. binning based on forward voltage,

luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

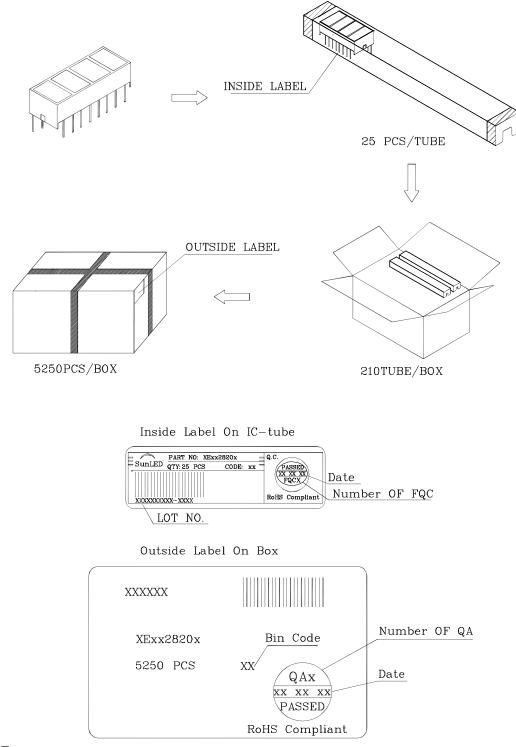
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



8.89mmx3.81mm LED LIGHT BAR

PACKING & LABEL SPECIFICATIONS



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- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
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